

MOSFET – P-Channel, POWER TRENCH®

-60 V, -13.5 A, 100 mΩ

FDMC5614P, FDMC5614P-L701

General Description

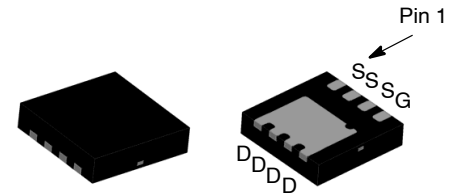
This P-Channel MOSFET is a rugged gate version of onsemi's advanced POWER TRENCH process. It has been optimized for power management applications requiring a wide range of gate drive voltage ratings (4.5 V – 20 V).

Features

- Max $r_{DS(on)}$ = 100 mΩ at $V_{GS} = -10$ V, $I_D = -5.7$ A
- Max $r_{DS(on)}$ = 135 mΩ at $V_{GS} = -4.5$ V, $I_D = -4.4$ A
- Low Gate Charge
- Fast Switching Speed
- High Performance Trench Technology for Extremely Low $r_{DS(on)}$
- High Power and Current Handling Capability
- These Devices are Pb-Free and are RoHS Compliant

Applications

- Power Management
- Load Switch
- Battery Protection



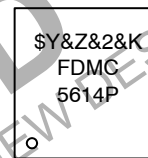
Top

Bottom

WDFN8 3.3x3.3, 0.65P
CASE 511DQ

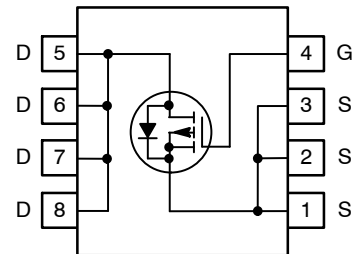
FDMC5614P, FDMC5614P-L701

MARKING DIAGRAM



\$Y = Logo
&Z = Assembly Location
&2 = Date Code (Year and Week)
&K = Lot Run Traceability Code
FDMC = Specific Device Code
5614P = Specific Device Code

PIN ASSIGNMENT



P-Channel MOSFET

ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

FDMC5614P, FDMC5614P-L701

MOSFET MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

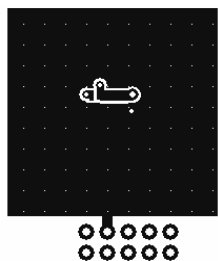
Symbol	Parameter			Rating	Unit
V_{DS}	Drain to Source Voltage			-60	V
V_{GS}	Gate to Source Voltage			± 20	V
I_D	Drain Current	Continuous (Package Limited)	$T_C = 25^\circ\text{C}$	-13.5	A
		Continuous (Silicon Limited)	$T_C = 25^\circ\text{C}$	-14	
		Continuous (Note 1a)	$T_A = 25^\circ\text{C}$	-5.7	
		Pulsed		-23	
P_D	Power Dissipation		$T_C = 25^\circ\text{C}$	42	W
	Power Dissipation (Note 1a)		$T_A = 25^\circ\text{C}$	2.1	
T_J, T_{STG}	Operating and Storage Junction Temperature Range			-55 to + 150	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

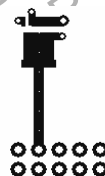
THERMAL CHARACTERISTICS

Symbol	Parameter	Rating	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	3.0	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	60	

- $R_{\theta JA}$ is determined with the device mounted on a 1 in² oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.
 - $R_{\theta JA} = 60^\circ\text{C/W}$ when mounted on a 1 in² pad of 2 oz copper, 1.5' x 1.5' x 0.062' thick PCB.
 - $R_{\theta JA} = 135^\circ\text{C/W}$ when mounted on a minimum pad of 2 oz copper.



a. 60°C/W when mounted on a 1 in² pad of 2 oz copper



b. 135°C/W when mounted on a minimum pad of 2 oz copper

- Pulse Test: Pulse Width < 300 μs , Duty cycle < 2.0%.

FDMC5614P, FDMC5614P-L701

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
--------	-----------	-----------------	-----	-----	-----	------

OFF CHARACTERISTICS

BV _{DSS}	Drain to Source Breakdown Voltage	I _D = -250 μA, V _{GS} = 0 V	-60	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I _D = -250 μA, referenced to 25°C	-	-54	-	mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -48 V, V _{GS} = 0 V	-	-	-1	μA
I _{GSS}	Gate to Source Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V	-	-	±100	nA

ON CHARACTERISTICS

V _{GS(th)}	Gate to Source Threshold Voltage	V _{GS} = V _{DS} , I _D = -250 μA	-1.0	-1.95	-3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I _D = -250 μA, referenced to 25°C	-	4.7	-	mV/°C
r _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = -10 V, I _D = -5.7 A	-	84	100	mΩ
		V _{GS} = -4.5 V, I _D = -4.4 A	-	108	135	
		V _{GS} = -10 V, I _D = -5.7 A, T _J = 125°C	-	140	168	
g _{FS}	Forward Transconductance	V _{DS} = -15 V, I _D = -5.7 A	-	11	-	S

DYNAMIC CHARACTERISTICS

C _{iss}	Input Capacitance	V _{DS} = -30 V, V _{GS} = 0 V, f = 1 MHz	-	795	1055	pF
C _{oss}	Output Capacitance		-	140	185	pF
C _{rss}	Reverse Transfer Capacitance		-	60	90	pF

SWITCHING CHARACTERISTICS

t _{d(on)}	Turn-On Delay Time	V _{DD} = -30 V, I _D = -1.0 A, V _{GS} = -10 V, R _{GEN} = 6 Ω	-	10	21	ns
t _r	Rise Time		-	11	23	ns
t _{d(off)}	Turn-Off Delay Time		-	32	65	ns
t _f	Fall Time		-	11	22	ns
Q _{g(TOT)}	Total Gate Charge at 10 V	V _{GS} = -10 V, V _{DD} = -30 V, I _D = -5.7 A	-	15	20	nC
Q _{gs}	Gate to Source Gate Charge		-	1.6	2.1	nC
Q _{gd}	Gate to Drain "Miller" Charge		-	2.7	3.5	nC

DRAIN-SOURCE DIODE CHARACTERISTICS

V _{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _S = -3.2 A	-	-0.8	-1.2	V
t _{rr}	Reverse Recovery Time	I _F = -3.2 A, di/dt = 100 A/μs	-	-	36	ns
Q _{rr}	Reverse Recovery Charge		-	-	29	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

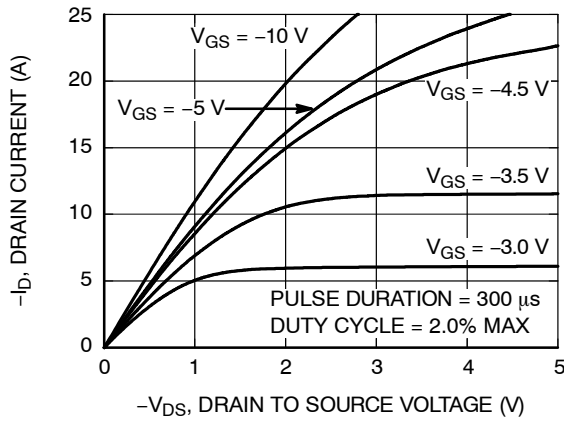


Figure 1. On Region Characteristics

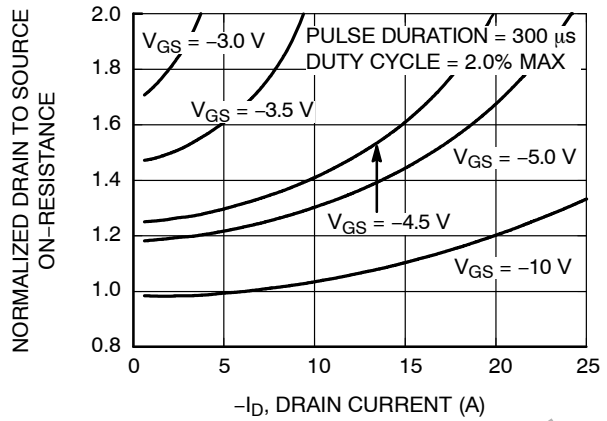


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

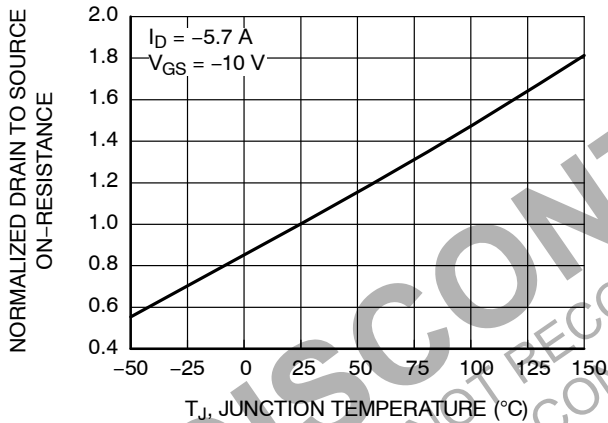


Figure 3. Normalized On Resistance vs. Junction Temperature

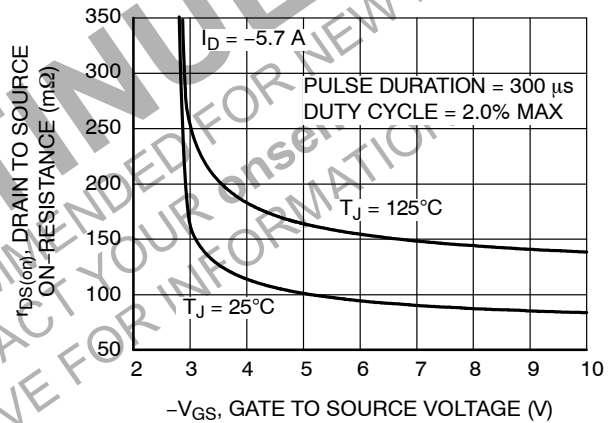


Figure 4. On-Resistance vs. Gate to Source Voltage

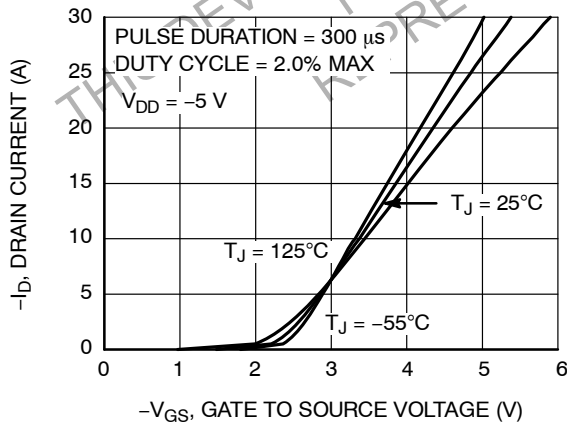


Figure 5. Transfer Characteristics

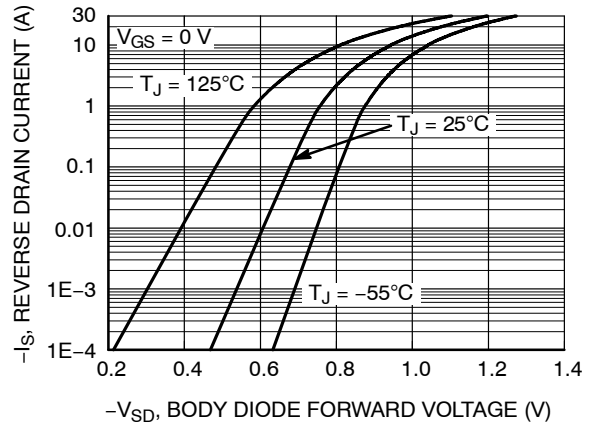


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

FDMC5614P, FDMC5614P-L701

TYPICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted) (continued)

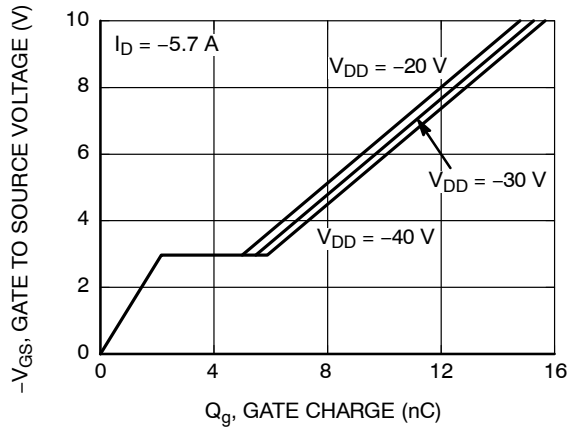


Figure 7. Gate Charge Characteristics

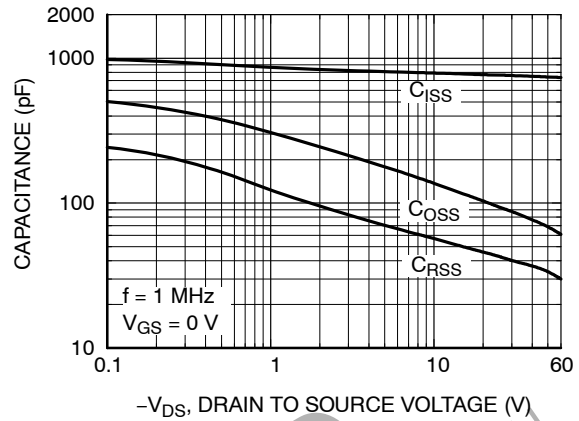


Figure 8. Capacitance vs. Drain to Source Voltage

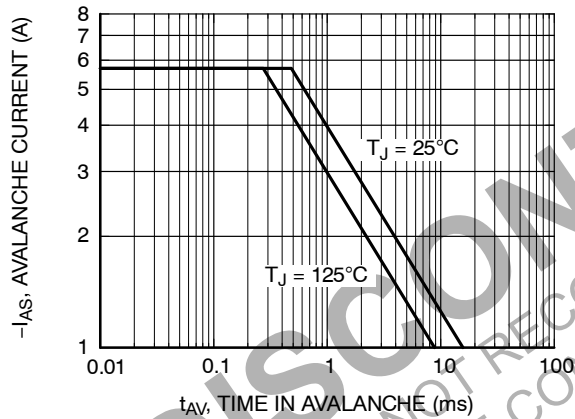


Figure 9. Unclamped Inductive Switching Capability

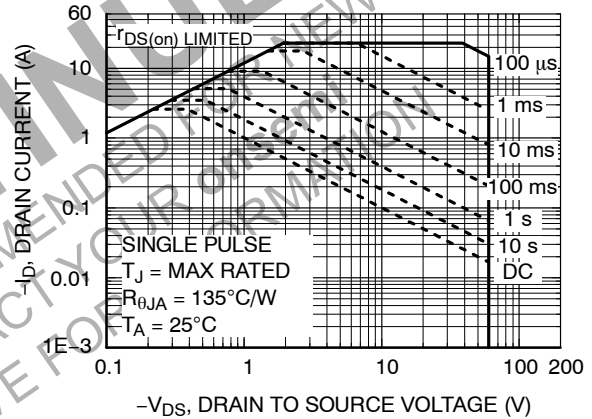


Figure 10. Forward Bias Safe Operating Area

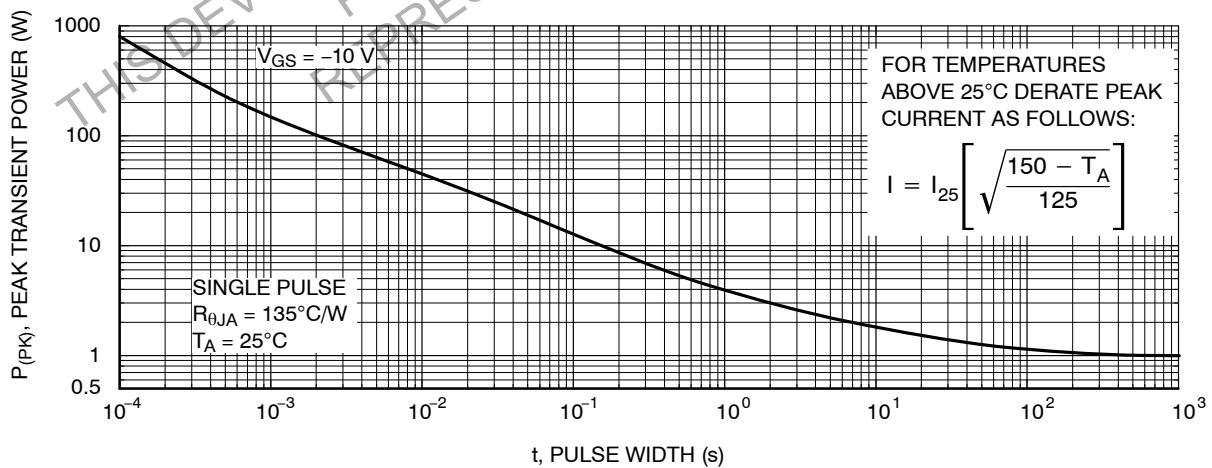


Figure 11. Single Pulse Maximum Power Dissipation

FDMC5614P, FDMC5614P-L701

TYPICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted) (continued)

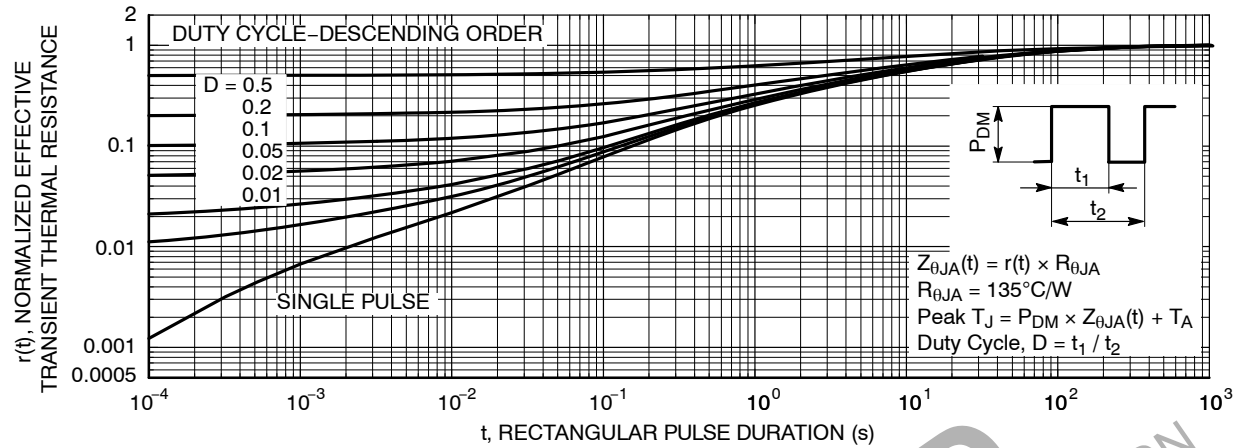


Figure 12. Transient Thermal Response Curve

ORDERING INFORMATION

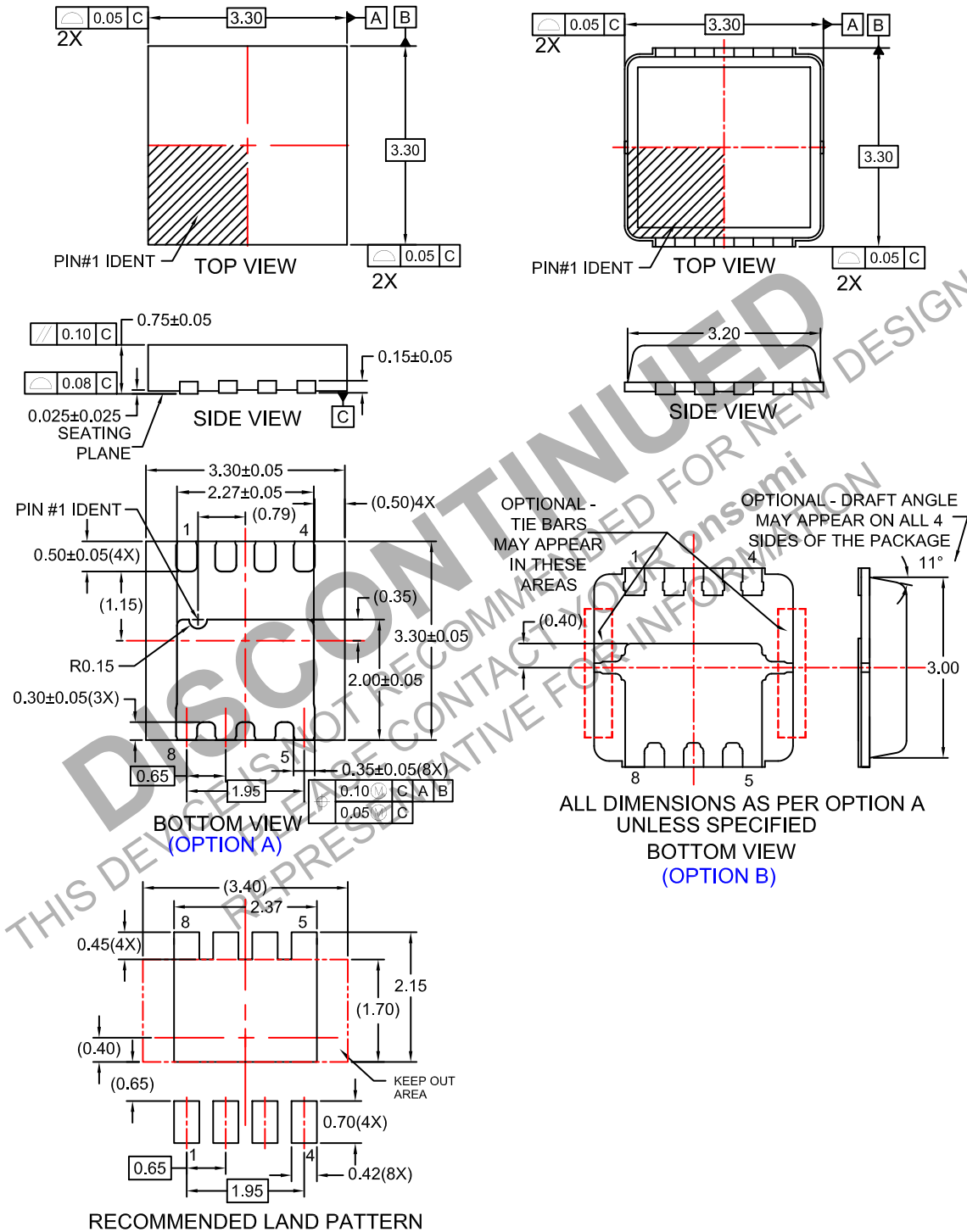
Device	Device Marking	Package Type	Reel Size	Tape Width	Shipping [†]
FDMC5614P	FDMC5614P	WDFN8 3.3x3.3, 0.65P Power 33 (Pb-Free)	7"	8 mm	3000 / Tape & Reel
FDMC5614P-L701	FDMC5614P	WDFN8 3.3x3.3, 0.65P Power 33 (Pb-Free)	7"	8 mm	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

WDFN8 3.3x3.3, 0.65P
CASE 511DQ
ISSUE O

DATE 31 OCT 2016



onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at
www.onsemi.com/support/sales